

Copper

SLOTOCOUP PRT 120 D

The Copper SLOTOCOUP PRT 120 D has been specifically developed for copper plating of PCBs if processes of direct plating are applied. SLOTOCOUP PRT 120 D ensures a quick covering in bore holes coupled with an excellent metal distribution. The copper layers deposited are fine grained, ductile and moderately bright.

The additives SLOTOCOUP PRT 121 D and SLOTOCOUP PRT 124 D are used for make-up as well as for continuous replenishment.

The concentration of the additives can be controlled by CVS. Therefore, an optimal control of the electrolyte is possible. Also over a longer operational period is no formation of disturbing decomposition products so a time-consuming active carbon treatment isn't necessary.

Copper SLOTOCOUP PRT 120 D can also be operated as a RPP (Reverse Pulse Plating) electrolyte.

The information in this data sheet is based on laboratory as well as practical experience. Figures quoted for operating limits and replenishment quantities are for guidance. Actual values necessary will depend on the components being plated (material and geometry), their application and plating plant conditions.

Important:

Please read this instruction carefully prior to the use of the process and carefully follow all the parameters that have a direct influence on the operation. We reserve the right to make technical changes. In the interest of safety, please pay attention to the hazard warnings on the labels of the containers. The minimum shelf life of the products is included on the labels and is also available in the appropriate Quality Assurance (QA03).

The current IMDS number of the layer deposited from the process is available on the internet at www.schloetter.com/downloads.

For the storage of chemical products the TRGS 510 must be followed.

If the additives used in this process contain a SVHC-substance, then this will be specified in the corresponding Material Safety Data Sheet, section 15.

